

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



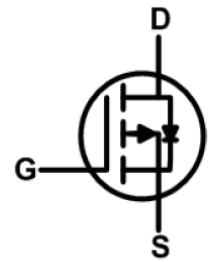
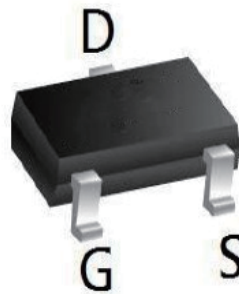
BVDSS	RDS(ON)	ID
-20V	13mΩ	-9.0A

Description

The 20P09L is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The 20P09L meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

SOT23-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V <sub>DS</sub>	Drain-to-Source Voltage	-20	V
V <sub>GS</sub>	Gate-to-Source Voltage	±12	V
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> = 25°C	-9
		T <sub>C</sub> = 100°C	-4
I <sub>DM</sub>	Pulsed Drain Current <sup>(1)</sup>	-66	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>(2)</sup>	28.8	mJ
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> = 25°C	30
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	41.6	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Junction & Storage Temperature Range	-55 to 150	°C

**Electrical Characteristics (T<sub>J</sub> =25 °C unless otherwise specified)**

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (T <sub>J</sub> = 25°C)	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V,	-	-	-1	μA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (T <sub>J</sub> = 100°C)	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V,	-	-	-100	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±12V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-0.65	-1	V
R <sub>DS(on)</sub>	Static Drain-Source onResistance <small>note2</small>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -8A	-	13	18	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -6A	-	17	23	
g <sub>fs</sub>	Forward Transconductance <sup>4</sup>	V <sub>DS</sub> =-4.5V, I <sub>D</sub> = -8A	-	36	-	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -10V, V <sub>GS</sub> =0V, f=1.0MHz	-	1630	-	pF
C <sub>oss</sub>	Output Capacitance		-	211	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	187	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	10	-	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -10V, I <sub>D</sub> = -8A, V <sub>GS</sub> = -4.5V	-	12	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	1.8	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	3.2	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = -4.5V, V <sub>DD</sub> = -10V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -8A	-	17	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	25.5	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	32	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	15	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = -8A	-	-	-1.2	V

**Note :**

- 1.Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
- 2.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>= -25V, V<sub>GS</sub>= -10V, L= 0.1mH, I<sub>AS</sub>= -24A
- 3.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
- 4.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- 5.This value is guaranteed by design hence it is not included in the production test..

Typical Performance Characteristics

Figure 1: Output Characteristics

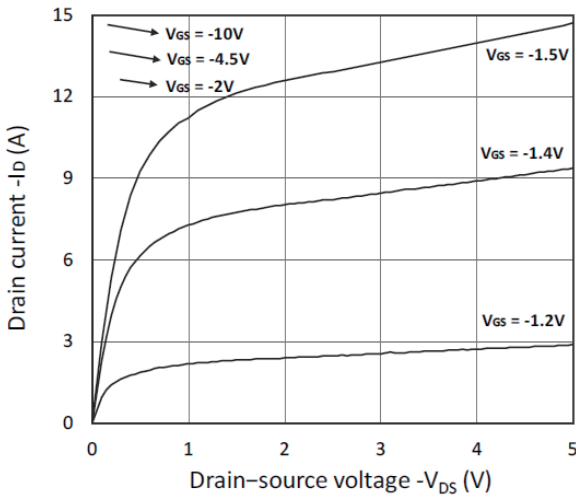


Figure 2: Transfer Characteristics

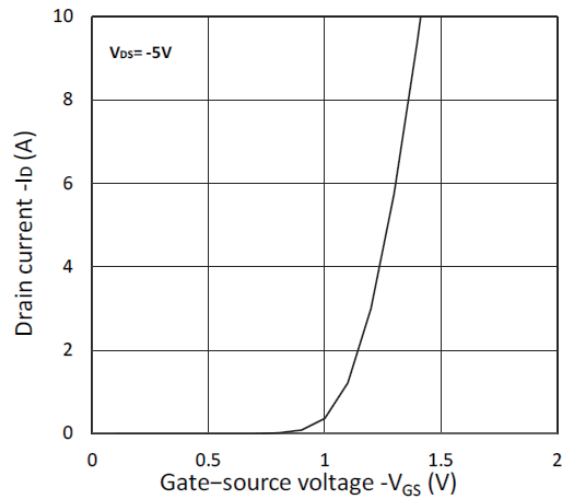


Figure 3: Forward Characteristics of Reverse

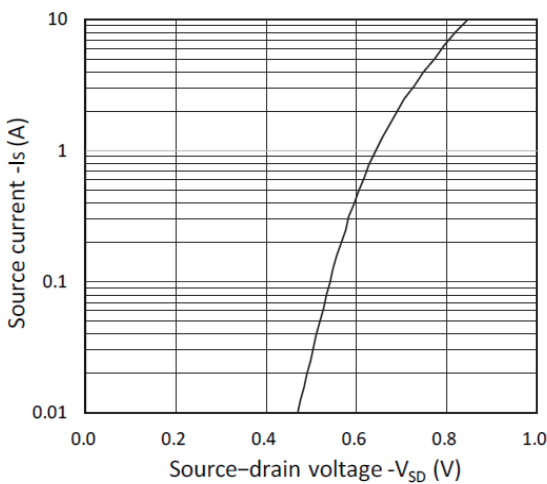


Figure 4: R\_DS(ON) vs. V\_GS

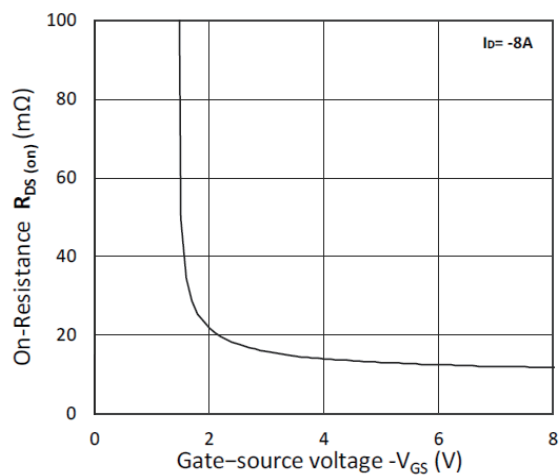


Figure 5: R\_DS(ON) vs. I\_D

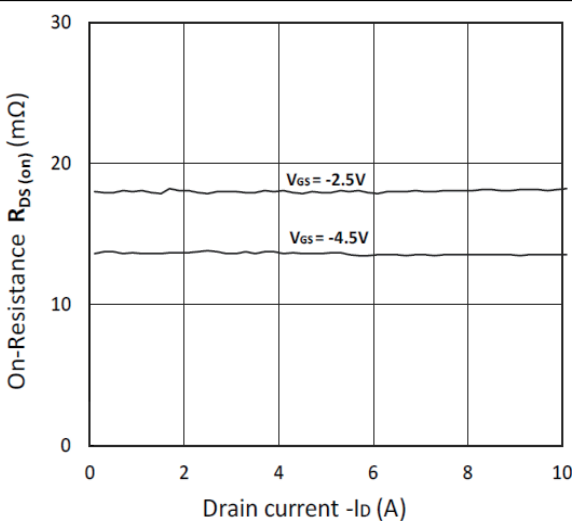
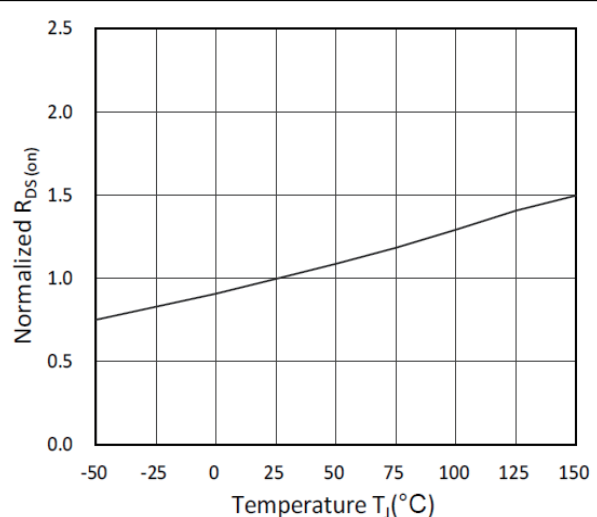


Figure 6: Normalized R\_DS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Temperature

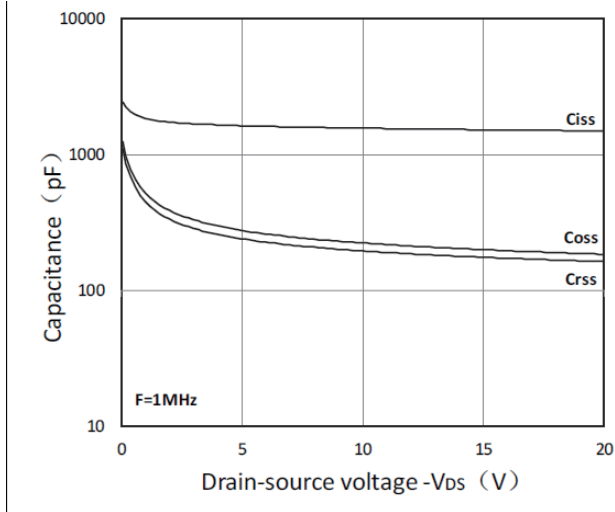


Figure 8: Gate Charge Characteristics

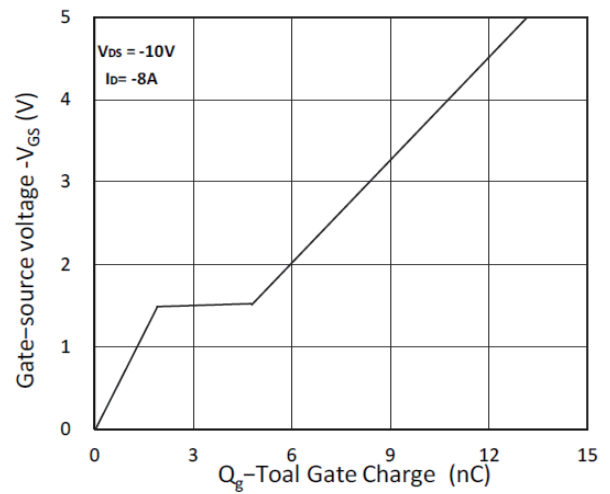


Figure 9: Power Dissipation Thermal Imp

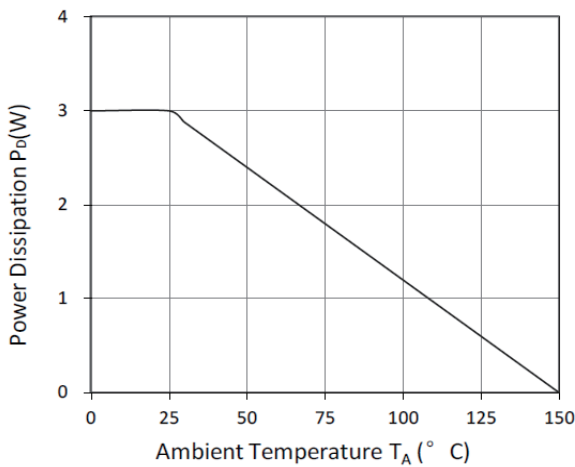


Figure 10: Power Dissipation

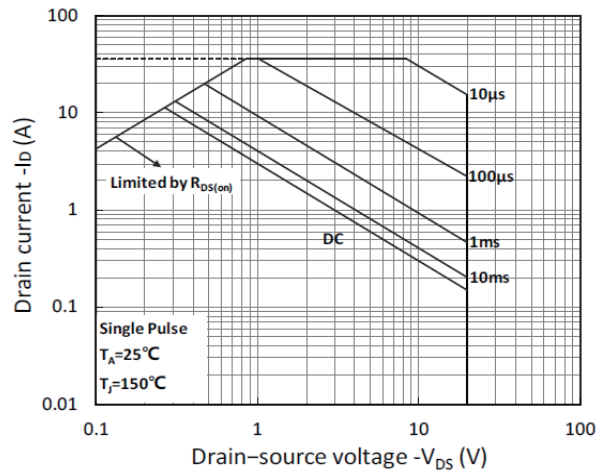
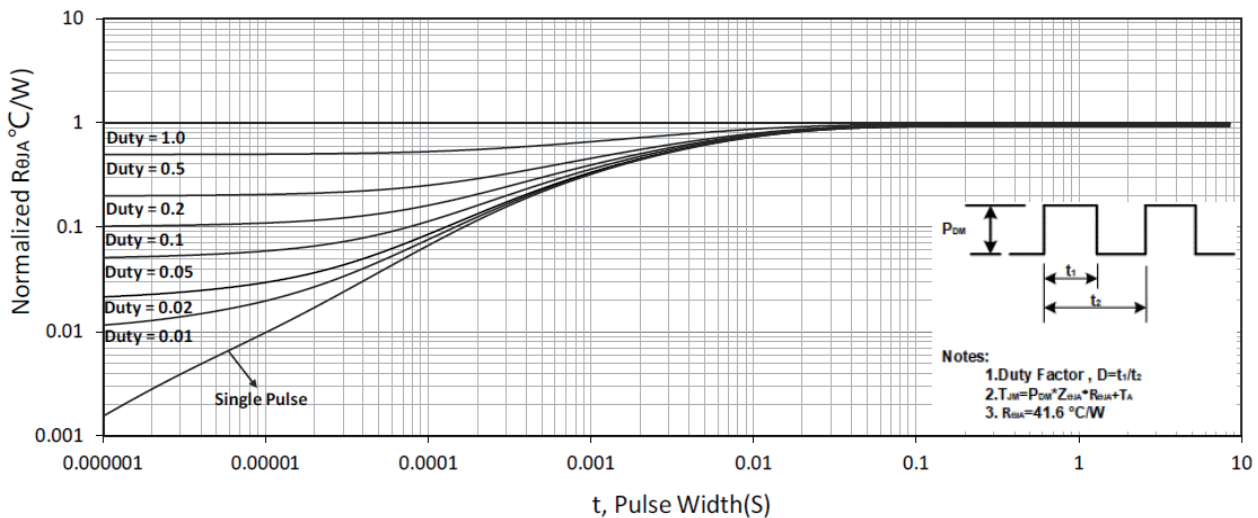
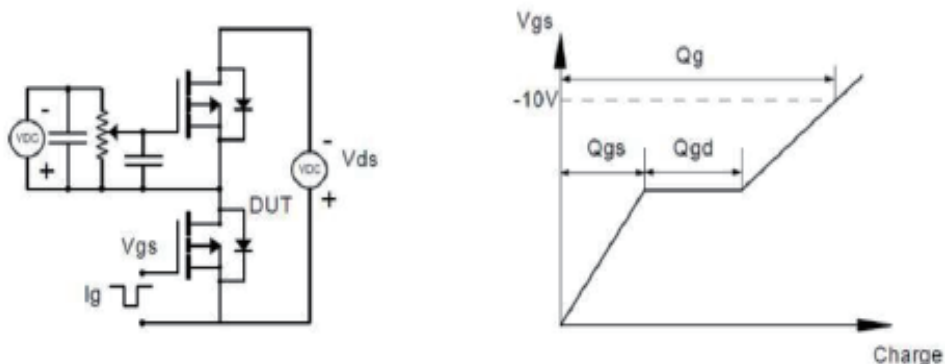


Figure.11: Safe Operating Area

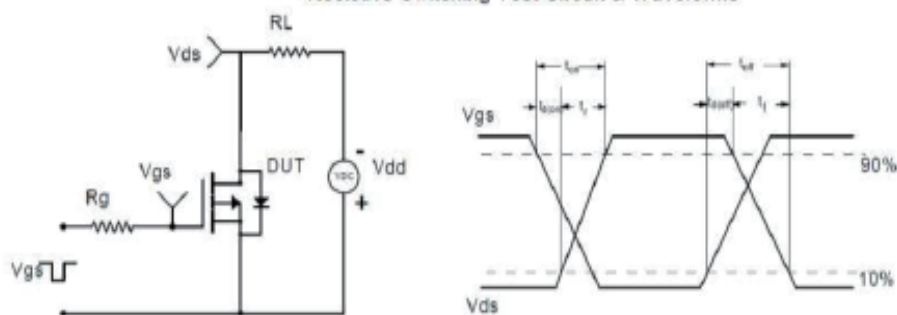


Test Circuit

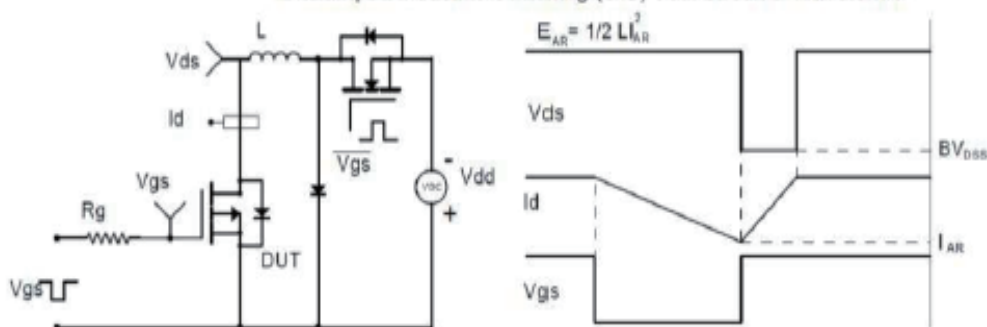
Gate Charge Test Circuit & Waveform



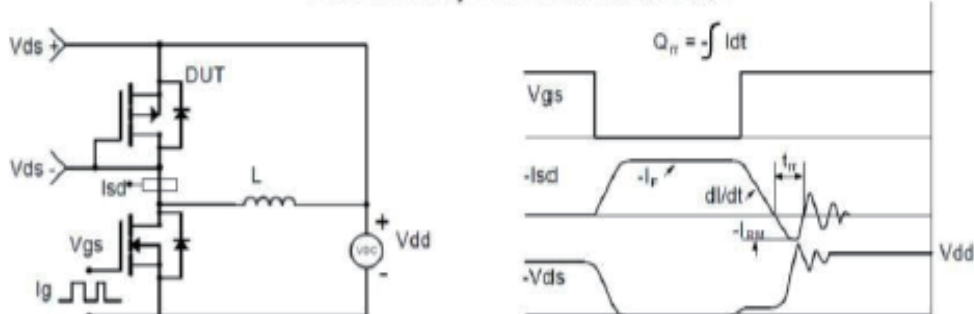
Resistive Switching Test Circuit & Waveforms



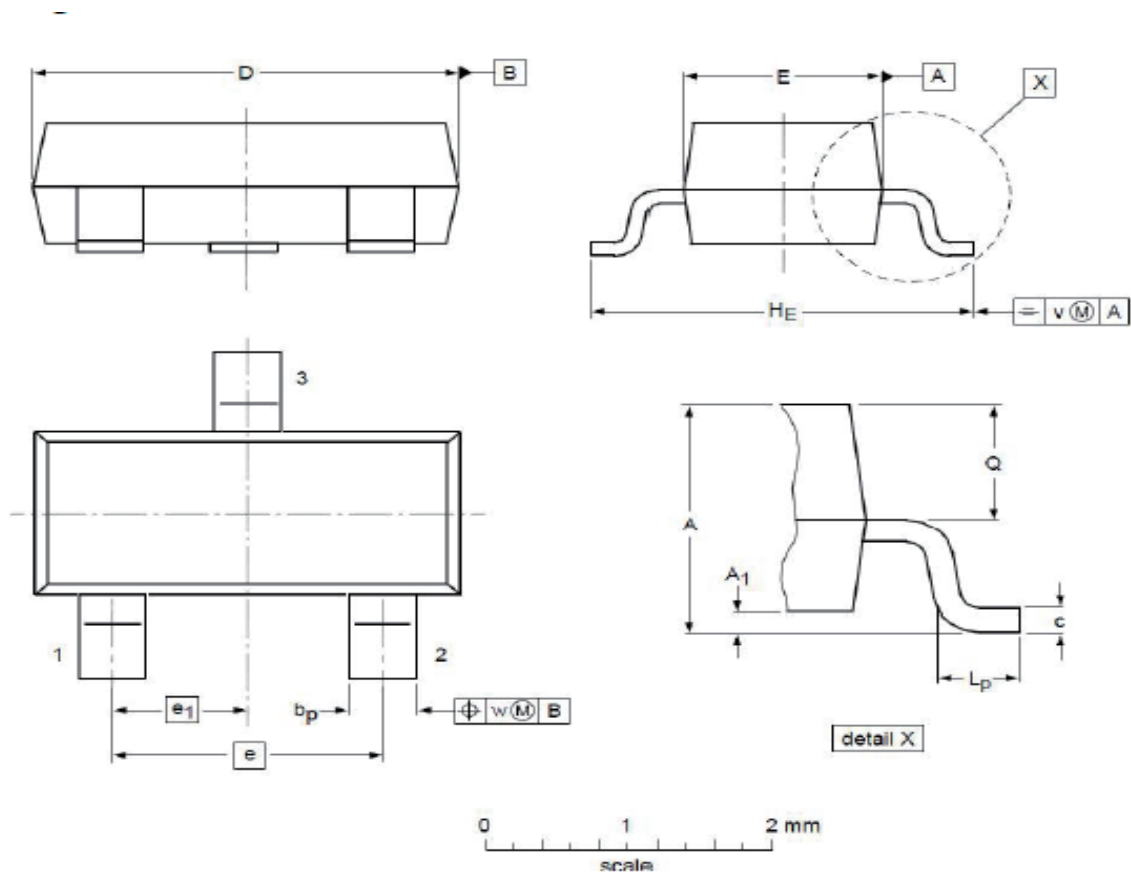
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.05	1.25	0.041	0.049
A1	0.00	0.10	0.000	0.004
A2	1.05	1.15	0.041	0.045
b	0.30	0.50	0.012	0.02
c	0.10	0.20	0.004	0.008
D	2.82	3.02	0.111	0.119
E	1.50	1.70	0.059	0.067
E1	2.65	2.95	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
L	0.30	0.60	0.012	0.024
θ	0°	8°	0°	8°